

# ENGINEERING DEPT.

# PRODUCT SPECIFICATION

For CJB1 Series DIP Solder Jacks

SPEC.NO.: SPCJ058A

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1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 105E	Sampling procedures for inspection by attributes
MIL - STD - 1344A	Test methods for electrical connectors
MIL - C - 39012C	General specification for connectors, coaxial, radio frequency
MIL - C - 45204	Gold plating (electrodeposited)

- 3. APPLICABLE SERIES NO.: CJB1 Series
- 4. SHAPE, CONSTRUCTION AND DIMENSIONS See attached drawings
- 5. MATERIALS See attached drawings
- 6. ACCOMMODATED P.C.BOARD6.1 Thickness: 1.6 mm (.063")6.2 P.C. Board Layout: See attached drawings



REVIEWED : Jacky APPROVED : Leno VERIFIED : Yong Xin .





## 8. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Rated current and voltage		1.5A 125V AC (r.m.s.)
8.2	Contact resistance	Dry circuit of DC 20 mV max. 100 mA max.	Less than 40 m $\Omega$
8.3	Dielectric strength	When applied AC 1000 V 1 minute between adjacent terminal. When applied AC 1500 V 1 minute between adjacent terminal.	No change
8.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 1000 $M\Omega$

#### 9. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Mating force	Measure force to mate samples at speed 25±3mm per minute with plug latch depressed	2.3 Kgf max.
9.2	Retention force (Between the Jack and Plug)	Retention speed 25±3mm per minute from Jack without latch	0.8 Kgf min.
9.3	Durability	Connector shall be subjected to 750 cycles of insertion and withdrawal	Contact resistance: Less than twice of initial



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### 10. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
10.1	Vibration	1.5 mm 10 - 55 - 10 HZ/minute each 2 hours for X,Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
10.2	Solder ability	Soldering time: 5±0.5 second Soldering pot: 230± 5°C	Minimum: 90% of immersed area
10.3	Resistance to soldering heat	Soldering time: 5±0.5 second Soldering pot: 260±5°C	No damage
10.4	Heat aging	65±2°C, 96 hours	No damage
10.5	Humidity	40±2°C, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 8-3
10.6	Temperature cycling	One cycle consists of : (1) $-55 {}^{+0}_{-3} \circ C$ , 30 min. (2)Room temp. 10-15 min. (3) $85 {}^{+3}_{-0} \circ C$ , 30 min. (4)Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial
10.7	Salt spray	Temperature: 35±3°C Solution: 5±1% Spray time: After 8hrs salt spray, dry 16hrs at room temp.(1-Cycle) After 3 Cycle cleaning by water and dry	Appearance: No damage Contact resistance: Less than twice of initial

## 11. AMBIENT TEMPERATURE RANGE: -40°C to + 105°C